

Appl. No. : 10/662,828
Filed : September 15, 2003

REMARKS

With this amendment, Claims 1-8 are pending in the above-captioned application. Claims 9-13 have been canceled. In view of the foregoing amendments and following remarks, Applicant respectfully requests reconsideration and allowance of the pending claims.

Priority

The Examiner indicated that specific reference to the earlier filed application must be made in the instant application if Applicant desires priority under 35 U.S.C. 121 based upon previously filed application. The Examiner also requested the Applicant to indicate the status of the nonprovisional parent applications. Pursuant to the Examiner's request, Applicant has amended the specification with an updated status of the nonprovisional parent application as well as other related applications incorporated by reference.

Claim Objections

The Examiner also objected to Claim 9 based on certain informalities. Applicant respectfully submits that this objection is moot in view of Applicant's cancellation of Claim 9.

Claim Rejections-35 U.S.C. 102

Claims 1-13 are rejected under 35 U.S.C. 102(e) as being anticipated by Farrar et al. (U.S. Pat. No. 6,747,347). The Examiner indicated that with respect to all the claims, Farrar discloses the claimed invention because the Farrar reference has the same disclosure.

Applicant respectfully disagrees with the Examiner's position and submits that Farrar does not have the identical disclosure as the present application. In fact, only a portion of the present application is the same as the Farrar disclosure. Moreover, Applicant notes that Farrar does not disclose each and every element recited in Claim 1. As such, Applicant respectfully submits that the pending claims cannot be anticipated by the Farrar reference.

Claim 9 is rejected under 35 U.S.C. 102(b) as being anticipated by Woodman (US Patent No. 4,868,712). Applicant respectfully submits that this rejection is moot in view of the cancellation of Claim 9.

Claim Rejections – 35 U.S.C. 103(a)

Claim 1 is rejected under 35 U.S.C. 103(a) as being unpatentable over Carson et al. (US 5,347,428) in view of Chall (EP 0 315 792). After carefully reviewing both references, Applicant notes that the references, either individually or in combination, do not teach or suggest a method of forming an electronic package module comprising bonding two chip stacks together

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to form a single module. Carson discloses methods of forming a single chip stack, which are generally known in the art. Chall discloses individual chips mounted on leadless chip carriers which can interface with other chip carriers. Chall is directed to providing a packaging scheme that uses standardizable modules carrying *planar mosaics* of many integrated circuit chips, which teaches away from stacking of the chips. (See, e.g., Column 2, Lines 14-27 of Chall) The Chall modules are placed in a standard module rack in which each module is plugged into connectors in the backplane. As such, Chall provides no motivation for one skilled in the art to bond chip stacks disclosed in Carson in the manner as recited in the pending claims. As such, the Applicant respectfully submits that the pending claims are patentable over Carson and Chall.

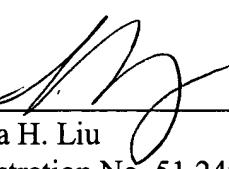
CONCLUSION

In view of the foregoing, Applicant respectfully submits that all pending claims of the present application are in condition for allowance, and such action is earnestly solicited. Should there be any impediment to the prompt allowance of this application that could be resolved through a telephone conference, the Examiner is respectfully requested to call the undersigned at the number shown below. Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Respectfully submitted,

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Dated: 9/28/2004

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